

#### **Technical Data Sheet**

#### 1.8mm Round Subminiature Infrared LED

#### HIR42-21C/L290/TR8

#### **Features**

- Compatible with infrared and vapor phase reflow solder process.
- Low forward voltage
- Good spectral matching to Si photodetector
- Pb free
- The product itself will remain within RoHS compliant version.

#### **Descriptions**

- HIR42-21C/L290/TR8 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view lens.
- The device is spectrally matched with silicon photodiode and phototransistor.



- PCB mounted infrared sensor
- Infrared emitting for miniature light barrier
- Floppy disk drive
- Optoelectronic switch
- Smoke detector

#### **Device Selection Guide**

Revision

: 1

I ED Dowt No	Chip	Long Color	
LED Part No.	Material	Lens Color	
HIR42-21C/L290/TR8	GaAlAs	Water clear	

Everlight Electronics Co., Ltd. http://www.everlight.com Rev 1 Page: 1 of 9

Device No: DIR-0000638 Prepared date: 01-10-2011 Prepared by: Hsin-Wei Ho

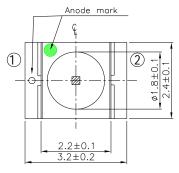
LifecyclePhase: Expired Period: Forever

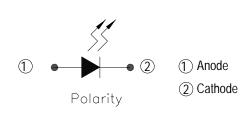


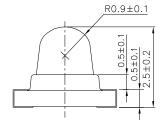
Release Date:2012-01-16 12:02:59.0



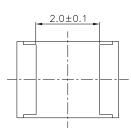
# **Package Dimensions**

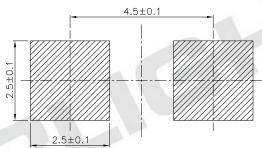












Notes: 1.All dimensions are in millimeters

2. Tolerances unless dimensions ±0.1mm

Everlight Electronics Co., Ltd. http://www.everlight.com Rev 1 Page: 2 of 9

Device No: DIR-0000638 Prepared date: 01-10-2011 Prepared by: Hsin-Wei Ho

Revision : 1 Release Date:2012-01-16 12:02:59.0



**Absolute Maximum Ratings (Ta=25°C)** 

Parameter	Symbol	Rating	Unit			
Continuous Forward Current	$I_{\mathrm{F}}$	100	mA			
Peak Forward Current *1	$I_{FP}$	1.0	A			
Reverse Voltage	$V_R$	5	V			
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C			
Storage Temperature	$T_{stg}$	-40 ~ +100	°C			
Soldering Temperature *2	$T_{sol}$	260	°C			
Junction temperature	Tj	115	°C			
Thermal resistance junction (ambient mounted on PC-board padsize 16mm <sup>2</sup> each)	$R_{thJA}$	400	°C/W			
Thermal resistance junction (Soldering point, mounted on metal block)	R <sub>thJS</sub>	300	°C/W			
Power Dissipation at(or below) 25 Free Air Temperature	$P_d$	200	mW			
<b>Notes:</b> *1:I <sub>FP</sub> ConditionsPulse	Width 10	00 µ s and Duty	1%.			
*2:Soldering time 5 sec	conds.					
C						
Electro-Optical Character	ristics (Ta	n=25°C)				
D ( C L )	120100 (10		3.41	/D	AT.	

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	
Radiant Intensity	Ie	$I_F=20mA$	7.0	14.0	1	mW/sr	
		$I_{FP}$ =150mA , Pulse Width 470 $\mu$ s ,Duty 1%	50	100	1		
Peak Wavelength	p	$I_F=20mA$		850		nm	
Spectral Bandwidth	Δλ	$I_F=20mA$		30	1	nm	
Forward Voltage V		$I_F=20mA$	1.2	1.4	1.7	V	
	$V_{\mathrm{F}}$	$I_{FP}\!\!=\!\!150mA$ , Pulse Width $$ 470 $\mu s$ ,Duty $$ 1%	1.4	1.75	2.0		
Reverse Current	$I_R$	$V_R=5V$			10	uA	
View Angle	2 1/2	$I_F=20mA$		35		Deg	

Everlight Electronics Co., Ltd. http://www.everlight.com Rev 1 Page: 3 of 9 Device No: DIR-0000638 Prepared date: 01-10-2011

Prepared by: Hsin-Wei Ho Revision Release Date:2012-01-16 12:02:59.0 : 1

正式發行 Approved LifecyclePhase: **Expired Period: Forever** 

<sup>\*2:</sup>Soldering time 5 seconds.

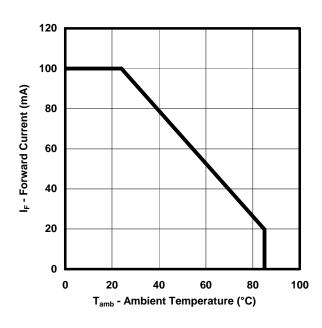


# **Typical Electro-Optical Characteristics Curves**

Fig.1 Forward Current vs.

Ambient Temperature

Fig.2 Spectral Distribution



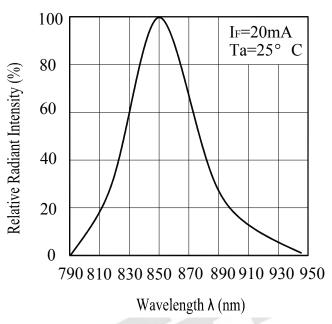


Fig.3 Peak Emission Wavelength
Ambient Temperature

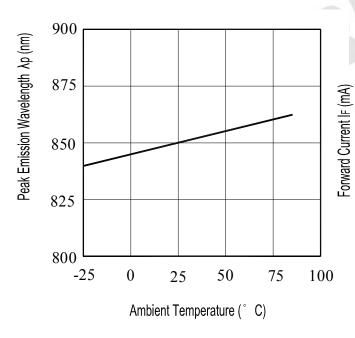
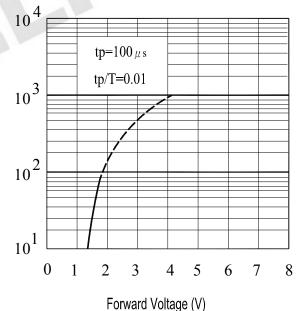


Fig.4 Forward Current vs. Forward Voltage



Everlight Electronics Co., Ltd.

Device No: DIR-0000638

Revision: 1

LifecyclePhase: 正式發行 Approved

http://www.everlight.com

Rev 1

Page: 4 of 9

Prepared date: 01-10-2011

11 Prepared by : Hsin-Wei Ho Release Date:2012-01-16 12:02:59.0

**Expired Period: Forever** 



# **Typical Electro-Optical Characteristics Curves**

Fig.5 Radiant Intensity vs.

Forward Current

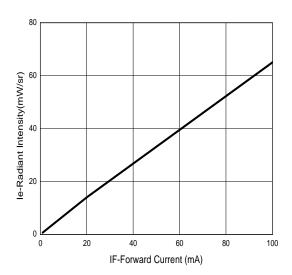
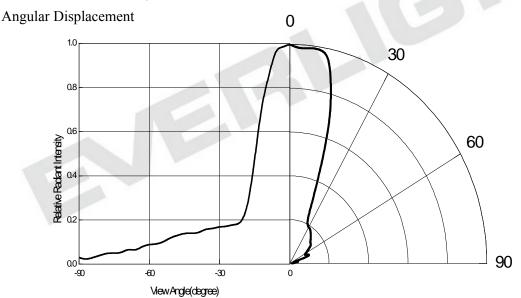


Fig.6 Relative Radiant Intensity vs.



Everlight Electronics Co., Ltd. http://www.everlight.com Rev 1 Page: 5 of 9

Device No: DIR-0000638 Prepared date: 01-10-2011 Prepared by: Hsin-Wei Ho

Revision : 1 Release Date:2012-01-16 12:02:59.0



#### **Precautions For Use**

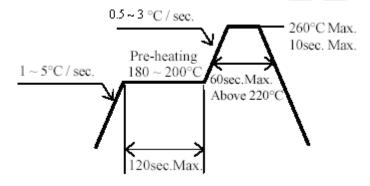
1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage(This part is compliant to JEDEC Level 3.)
  - 2.1 Do not open moisture proof bag before the products are ready to use.
  - 2.2 Before opening the package, the LEDs should be kept at 30 or less and 90%RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30 or less and 60%RH or less.
- 2.5 The LEDs should be used within 168 hours (7 days) after opening the package.
- 2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5 , 48hours.

- 3. Soldering Condition
- 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

Everlight Electronics Co., Ltd. http://www.everlight.com Rev 1 Page: 6 of 9

LifecyclePhase: Approved Expired Period: Forever

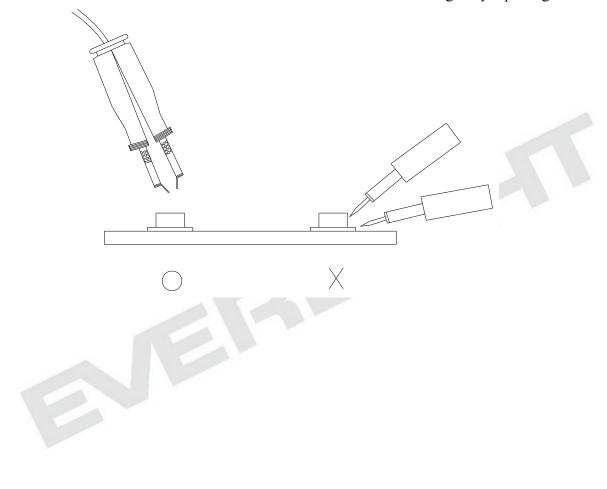


#### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350 for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 5.Repairing

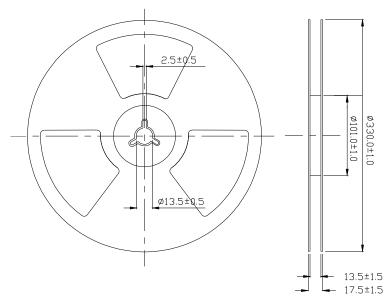
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



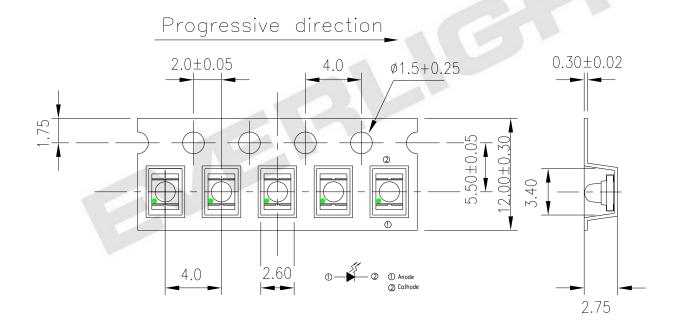
Everlight Electronics Co., Ltd. http://www.everlight.com Rev 1 Page: 7 of 9



### **Package Dimensions**



#### Carrier Tape Dimensions: (Quantity: 2500pcs/reel)



Unit: mm

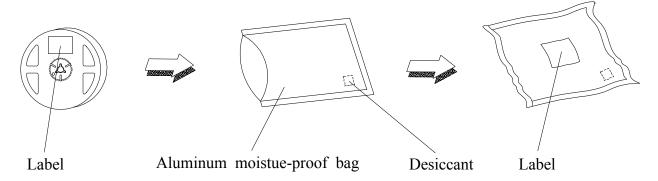
Everlight Electronics Co., Ltd. http://www.everlight.com Rev 1 Page: 8 of 9

Device No: DIR-0000638 Prepared date: 01-10-2011 Prepared by: Hsin-Wei Ho
Revision: 1 Release Date: 2012-01-16 12:02:59.0

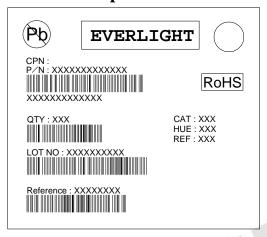
LifecyclePhase: Approved Expired Period: Forever



#### **Packing Procedure**



#### **Label Form Specification**



CPN: Customer's Production Number

P/N : Production Number QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

#### **Notes**

- 1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
- 3. These specification sheets include materials protected under copyright of EVERLIGHT corporation. Please don't reproduce or cause anyone to reproduce them without EVERLIGHT's consent.

EVERLIGHT ELECTRONICS CO., LTD.

Office: No. 6-8,Zhonghua Rd.,Shulin Dist., New Taipei City 23860,Taiwan, R.O.C Tel: 886-2-2685-6688 Fax: 886-2-2685-6897 http://www.everlight.com

Everlight Electronics Co., Ltd. http://www.everlight.com Rev 1 Page: 9 of 9

Device No: DIR-0000638 Prepared date: 01-10-2011 Prepared by: Hsin-Wei Ho

Revision: 1 Release Date: 2012-01-16 12:02:59.0